

**STRUCTURE OF PACKAGE FOR SEMICONDUCTOR IMAGE PICKUP DEVICE
AND FABRICATION METHOD TEHREOF**

ABSTRACT OF THE DISCLOSURE

5 A package for semiconductor image pickup device is provided. The package is fabricated by using flip chip bumping. During deposition process of forming a metallic bonding layer and a metal layer for plating, a surface of a semiconductor image pickup device is maintained at the range between room temperature and 200°C in accordance with a first embodiment. A polymer layer for preventing stress from generating can absorb stress
10 generated during the deposition process in accordance with a second embodiment. According to the present invention, a functional polymer layer on the surface of a semiconductor image pickup device can be prevent from being deteriorated in its properties and from transforming at its surface.

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